



xLED-VOS-4550 Pin Fin LED Heat Sink Φ45mm for Vossloh-Schwabe

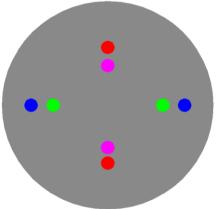
Features VS Benefits

- * The xLED-VOS-4550 Vossloh-Schwabe Pin Fin LED Heat Sinks are specifically designed for luminaires using the Vossloh-Schwabe LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 400 to 1,500 lumen.
- * Thermal resistance range Rth 5.55°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Vossloh-Schwabe COB series.
- * Diameter 45.0mm standard height 50.0mm Other heights on request.
- * Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Vossloh-Schwabe COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.





Vossloh-Schwabe LED Modules directly Mounting Options Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (13.5*13.5): :

AAG.STUCCHI: 8100-G2

Direct mounting with machine screws M3x6.5mm

Vossloh-Schwabe LUGA Shop Gen. 5/ Gen.6 COB Series (19.0*19.0):

DMS125***G: DMS126***H; DMS126***G; DMS128***G;

Vossloh-Schwabe LUGA Shop TW COB Series:

Direct mounting with machine screws M3x6.5mm.





Mounting Options and Drawings & Dimensions

Example:xLED-VOS-4550-B-1,2

Example:xLED-VOS-45

Height (mm)

Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

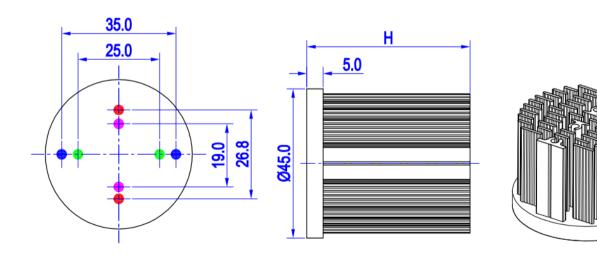
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

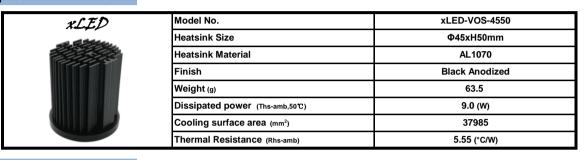
MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	COB series (13.5*13.5)	/	М3	6.5mm	19.0mm/ 2-@180°
2		BJB Holder 47.319.6294.50	М3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		AAG.STUCCHI 8100-G2	МЗ	6.5mm	
3	COB series (19.0*19.0)	/			26.8mm/ 2-@180°
4		BJB Holder 47.319.2021.50			35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8101-G2			







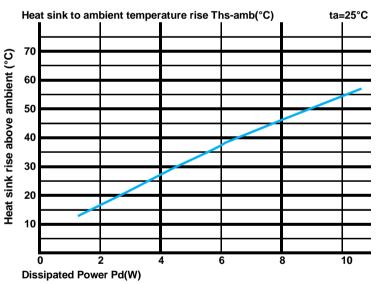
The product deta table



The thermal data table

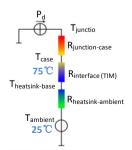
- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (1 \eta L)$.
- Pd Dissipated power; Pe Electrical power; $\eta L = \text{Light effciency of the LED module}$;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		xLED-VOS-4550		
Dissipated Power Pd(W)	2.0	8.00	16.0	
	4.0	6.50	26.0	
	6.0	6.17	37.0	
	8.0	5.75	46.0	
	10.0	5.40	54.0	



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

 MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.
- Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- $\theta\,$ Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface}}$ (TIM) [°C,M], the thermal resistance with the heat sink is $R_{\text{heatsrik-ambent}}$ [°C,M], and the ambient temperature is T_{ambent} [°C].
- *Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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